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(71)Applicant : MITSUBISHI ELECTRIC CORP

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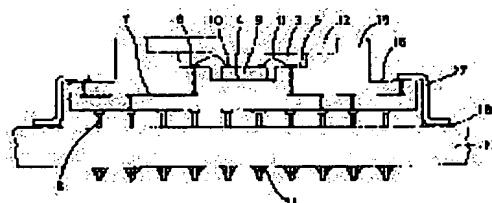
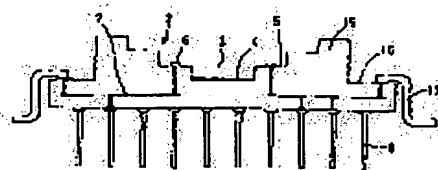
(72)Inventor : NAKAO SHIN

(54) SEMICONDUCTOR PACKAGE

(57)Abstract:

PURPOSE: To be able to improve the packaging density of semiconductor elements without increasing the size of a whole semiconductor package as the conventional one by leading out input/output leads for electrically connecting the semiconductor element to the exterior of the package from the side surface of the package.

CONSTITUTION: Input/output leads 17 led from the side surface of a semiconductor package which contains a semiconductor element 9 and has input/output pins 8 on the rear surface for electrically connecting the element 9 to the exterior of the semiconductor package are provided on the semiconductor package. For example, a step 16 is formed on the side surface of the periphery of a package substrate 15, and a plurality of the leads 17 for electrically connecting the element 9 contained in the substrate 15 to the exterior of the substrate 15 are led from the step 16 at predetermined pitches. A bonding pad 6 is electrically connected to the pins 8 and the leads 17 by wirings 7 in the substrate 15.



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